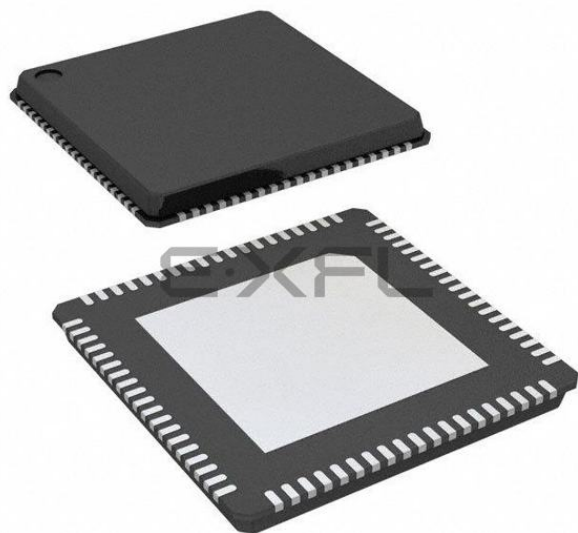




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	FT32
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	CANbus, I ² C, SPI, UART/USART, USB
Peripherals	POR, PWM, WDT
Number of I/O	42
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	320K x 8
Voltage - Supply (Vcc/Vdd)	2.97V ~ 3.63V
Data Converters	A/D 4x10b; D/A 2x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	76-VFQFN Exposed Pad
Supplier Device Package	76-QFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/bridgetek/ft907q-t

Table 3. Pin descriptionLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
Multiplexed digital pins								
P0_0	L3	K3	G2	32	[2]	N; PU	I/O	GPIO0[0] — General purpose digital input/output pin.
							I/O	SSP1_MISO — Master In Slave Out for SSP1.
							I	ENET_RXD1 — Ethernet receive data 1 (RMII/MII interface).
							I/O	SGPIO0 — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	I2S0_TX_WS — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
P0_1	M2	K2	G1	34	[2]	N; PU	I/O	GPIO0[1] — General purpose digital input/output pin.
							I/O	SSP1_MOSI — Master Out Slave in for SSP1.
							I	ENET_COL — Ethernet Collision detect (MII interface).
							I/O	SGPIO1 — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	ENET_TX_EN — Ethernet transmit enable (RMII/MII interface).
P1_0	P2	L1	H1	38	[2]	N; PU	I/O	GPIO0[4] — General purpose digital input/output pin.
							I	CTIN_3 — SCTimer/PWM input 3. Capture input 1 of timer 1.
							I/O	EMC_A5 — External memory address line 5.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SSP0_SSEL — Slave Select for SSP0.
							I/O	SGPIO7 — General purpose digital input/output pin.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P1_1	R2	N1	K2	42	[2]	N; PU	I/O	GPIO0[8] — General purpose digital input/output pin. Boot pin (see Table 5).
							O	CTOUT_7 — SCTimer/PWM output 7. Match output 3 of timer 1.
							I/O	EMC_A6 — External memory address line 6.
							I/O	SGPIO8 — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SSP0_MISO — Master In Slave Out for SSP0.
							-	R — Function reserved.
P1_2	R3	N2	K1	43	[2]	N; PU	I/O	GPIO0[9] — General purpose digital input/output pin. Boot pin (see Table 5).
							O	CTOUT_6 — SCTimer/PWM output 6. Match output 2 of timer 1.
							I/O	EMC_A7 — External memory address line 7.
							I/O	SGPIO9 — General purpose digital input/output pin.
							-	R — Function reserved.
							I/O	SSP0_MOSI — Master Out Slave in for SSP0.
							-	R — Function reserved.
P1_3	P5	M2	J1	44	[2]	N; PU	I/O	GPIO0[10] — General purpose digital input/output pin.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
							I/O	SGPIO10 — General purpose digital input/output pin.
							O	EMC_OE — LOW active Output Enable signal.
							O	USB0_IND1 — USB0 port indicator LED control output 1.
							I/O	SSP1_MISO — Master In Slave Out for SSP1.
							-	R — Function reserved.
P1_4	T3	P2	J2	47	[2]	N; PU	O	SD_RST — SD/MMC reset signal for MMC4.4 card.
							I/O	GPIO0[11] — General purpose digital input/output pin.
							O	CTOUT_9 — SCTimer/PWM output 9. Match output 3 of timer 3.
							I/O	SGPIO11 — General purpose digital input/output pin.
							O	EMC_BLS0 — LOW active Byte Lane select signal 0.
							O	USB0_IND0 — USB0 port indicator LED control output 0.
							I/O	SSP1_MOSI — Master Out Slave in for SSP1.
							-	R — Function reserved.
							O	SD_VOLT1 — SD/MMC bus voltage select output 1.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P2_8	J16	H14	C6	98	[2]	N; PU	I/O	SGPIO15 — General purpose digital input/output pin. Boot pin (see Table 5).
							O	CTOUT_0 — SCTimer/PWM output 0. Match output 0 of timer 0.
							I/O	U3_DIR — RS-485/EIA-485 output enable/direction control for USART3.
							I/O	EMC_A8 — External memory address line 8.
							I/O	GPIO5[7] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
P2_9	H16	G14	B10	102	[2]	N; PU	I/O	GPIO1[10] — General purpose digital input/output pin. Boot pin (see Table 5).
							O	CTOUT_3 — SCTimer/PWM output 3. Match output 3 of timer 0.
							I/O	U3_BAUD — Baud pin for USART3.
							I/O	EMC_A0 — External memory address line 0.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P2_10	G16	F14	E8	104	[2]	N; PU	I/O	GPIO0[14] — General purpose digital input/output pin.
							O	CTOUT_2 — SCTimer/PWM output 2. Match output 2 of timer 0.
							O	U2_TXD — Transmitter output for USART2.
							I/O	EMC_A1 — External memory address line 1.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
P2_11	F16	E13	A9	105	[2]	N; PU	I/O	GPIO1[11] — General purpose digital input/output pin.
							O	CTOUT_5 — SCTimer/PWM output 5. Match output 3 of timer 3.
							I	U2_RXD — Receiver input for USART2.
							I/O	EMC_A2 — External memory address line 2.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
P7_0	B16	B14	-	110	[2]	N; PU	I/O	GPIO3[8] — General purpose digital input/output pin.
							O	CTOUT_14 — SCTimer/PWM output 14. Match output 2 of timer 3.
							-	R — Function reserved.
							O	LCD_LE — Line end signal.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SGPIO4 — General purpose digital input/output pin.
P7_1	C14	C13	-	113	[2]	N; PU	I/O	GPIO3[9] — General purpose digital input/output pin.
							O	CTOUT_15 — SCTimer/PWM output 15. Match output 3 of timer 3.
							I/O	I2S0_TX_WS — Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the <i>I²S-bus specification</i> .
							O	LCD_VD19 — LCD data.
							O	LCD_VD7 — LCD data.
							-	R — Function reserved.
							O	U2_TXD — Transmitter output for USART2.
							I/O	SGPIO5 — General purpose digital input/output pin.
P7_2	A16	A14	-	115	[2]	N; PU	I/O	GPIO3[10] — General purpose digital input/output pin.
							I	CTIN_4 — SCTimer/PWM input 4. Capture input 2 of timer 1.
							I/O	I2S0_TX_SDA — I2S transmit data. It is driven by the transmitter and read by the receiver. Corresponds to the signal SD in the <i>I²S-bus specification</i> .
							O	LCD_VD18 — LCD data.
							O	LCD_VD6 — LCD data.
							-	R — Function reserved.
							I	U2_RXD — Receiver input for USART2.
							I/O	SGPIO6 — General purpose digital input/output pin.
							I/O	GPIO3[11] — General purpose digital input/output pin.
P7_3	C13	C12	-	117	[2]	N; PU	I	CTIN_3 — SCTimer/PWM input 3. Capture input 1 of timer 1.
							-	R — Function reserved.
							O	LCD_VD17 — LCD data.
							O	LCD_VD5 — LCD data.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PA_3	H11	E10	-	-	[3]	N; PU	I/O	GPIO4[10] — General purpose digital input/output pin.
							I	QEI_PHA — Quadrature Encoder Interface PHA input.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
PA_4	G13	E12	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_9 — SCTimer/PWM output 9. Match output 3 of timer 3.
							-	R — Function reserved.
							I/O	EMC_A23 — External memory address line 23.
							I/O	GPIO5[19] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PB_0	B15	D14	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_10 — SCTimer/PWM output 10. Match output 3 of timer 3.
							O	LCD_VD23 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[20] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PB_1	A14	A13	-	-	[2]	N; PU	-	R — Function reserved.
							I	USB1_ULPI_DIR — ULPI link DIR signal. Controls the ULP data line direction.
							O	LCD_VD22 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[21] — General purpose digital input/output pin.
							O	CTOUT_6 — SCTimer/PWM output 6. Match output 2 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PB_2	B12	B11	-	-	[2]	N; PU	-	R — Function reserved.
							I/O	USB1_ULPI_D7 — ULPI link bidirectional data line 7.
							O	LCD_VD21 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[22] — General purpose digital input/output pin.
							O	CTOUT_7 — SCTimer/PWM output 7. Match output 3 of timer 1.
							-	R — Function reserved.
							-	R — Function reserved.
PB_3	A13	A12	-	-	[2]	N; PU	-	R — Function reserved.
							I/O	USB1_ULPI_D6 — ULPI link bidirectional data line 6.
							O	LCD_VD20 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[23] — General purpose digital input/output pin.
							O	CTOUT_8 — SCTimer/PWM output 8. Match output 0 of timer 2.
							-	R — Function reserved.
PB_4	B11	B10	-	-	[2]	N; PU	-	R — Function reserved.
							I/O	USB1_ULPI_D5 — ULPI link bidirectional data line 5.
							O	LCD_VD15 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[24] — General purpose digital input/output pin.
							I	CTIN_5 — SCTimer/PWM input 5. Capture input 2 of timer 2.
							-	R — Function reserved.
PB_5	A12	A11	-	-	[2]	N; PU	-	R — Function reserved.
							I/O	USB1_ULPI_D4 — ULPI link bidirectional data line 4.
							O	LCD_VD14 — LCD data.
							-	R — Function reserved.
							I/O	GPIO5[25] — General purpose digital input/output pin.
							I	CTIN_7 — SCTimer/PWM input 7.
							O	LCD_PWR — LCD panel power enable.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PD_8	P8	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	CTIN_6 — SCTimer/PWM input 6. Capture input 1 of timer 3.
							I/O	EMC_D22 — External memory data line 22.
							-	R — Function reserved.
							I/O	GPIO6[22] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	SGPIO12 — General purpose digital input/output pin.
PD_9	T11	-	-	-	[2]	N; PU	-	R — Function reserved.
							O	CTOUT_13 — SCTimer/PWM output 13. Match output 3 of timer 3.
							I/O	EMC_D23 — External memory data line 23.
							-	R — Function reserved.
							I/O	GPIO6[23] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PD_10	P11	-	-	-	[2]	N; PU	-	R — Function reserved.
							I	CTIN_1 — SCTimer/PWM input 1. Capture input 1 of timer 0. Capture input 1 of timer 2.
							O	EMC_BLS3 — LOW active Byte Lane select signal 3.
							-	R — Function reserved.
							I/O	GPIO6[24] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
PD_11	N9	M7	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							O	EMC_CS3 — LOW active Chip Select 3 signal.
							-	R — Function reserved.
							I/O	GPIO6[25] — General purpose digital input/output pin.
							I/O	USB1_ULPI_D0 — ULPI link bidirectional data line 0.
							O	CTOUT_14 — SCTimer/PWM output 14. Match output 2 of timer 3.
							-	R — Function reserved.

Table 3. Pin description ...continuedLCD, Ethernet, USB0, and USB1 functions are not available on all parts. See [Table 2](#).

Symbol	LBGA256	TFBGA180	TFBGA100	LQFP144		Reset state [1]	Type	Description
PD_16	R14	P12	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							I/O	EMC_A16 — External memory address line 16.
							-	R — Function reserved.
							I/O	GPIO6[30] — General purpose digital input/output pin.
							O	SD_VOLT2 — SD/MMC bus voltage select output 2.
							O	CTOUT_12 — SCTimer/PWM output 12. Match output 3 of timer 3.
							-	R — Function reserved.
PE_0	P14	N12	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	EMC_A18 — External memory address line 18.
							I/O	GPIO7[0] — General purpose digital input/output pin.
							O	CAN1_TD — CAN1 transmitter output.
							-	R — Function reserved.
							-	R — Function reserved.
PE_1	N14	M12	-	-	[2]	N; PU	-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.
							I/O	EMC_A19 — External memory address line 19.
							I/O	GPIO7[1] — General purpose digital input/output pin.
							I	CAN1_RD — CAN1 receiver input.
							-	R — Function reserved.
							-	R — Function reserved.
PE_2	M14	L12	-	-	[2]	N; PU	I	ADCTRIG0 — ADC trigger input 0.
							I	CAN0_RD — CAN receiver input.
							-	R — Function reserved.
							I/O	EMC_A20 — External memory address line 20.
							I/O	GPIO7[2] — General purpose digital input/output pin.
							-	R — Function reserved.
							-	R — Function reserved.
							-	R — Function reserved.

7.5 AHB multilayer matrix

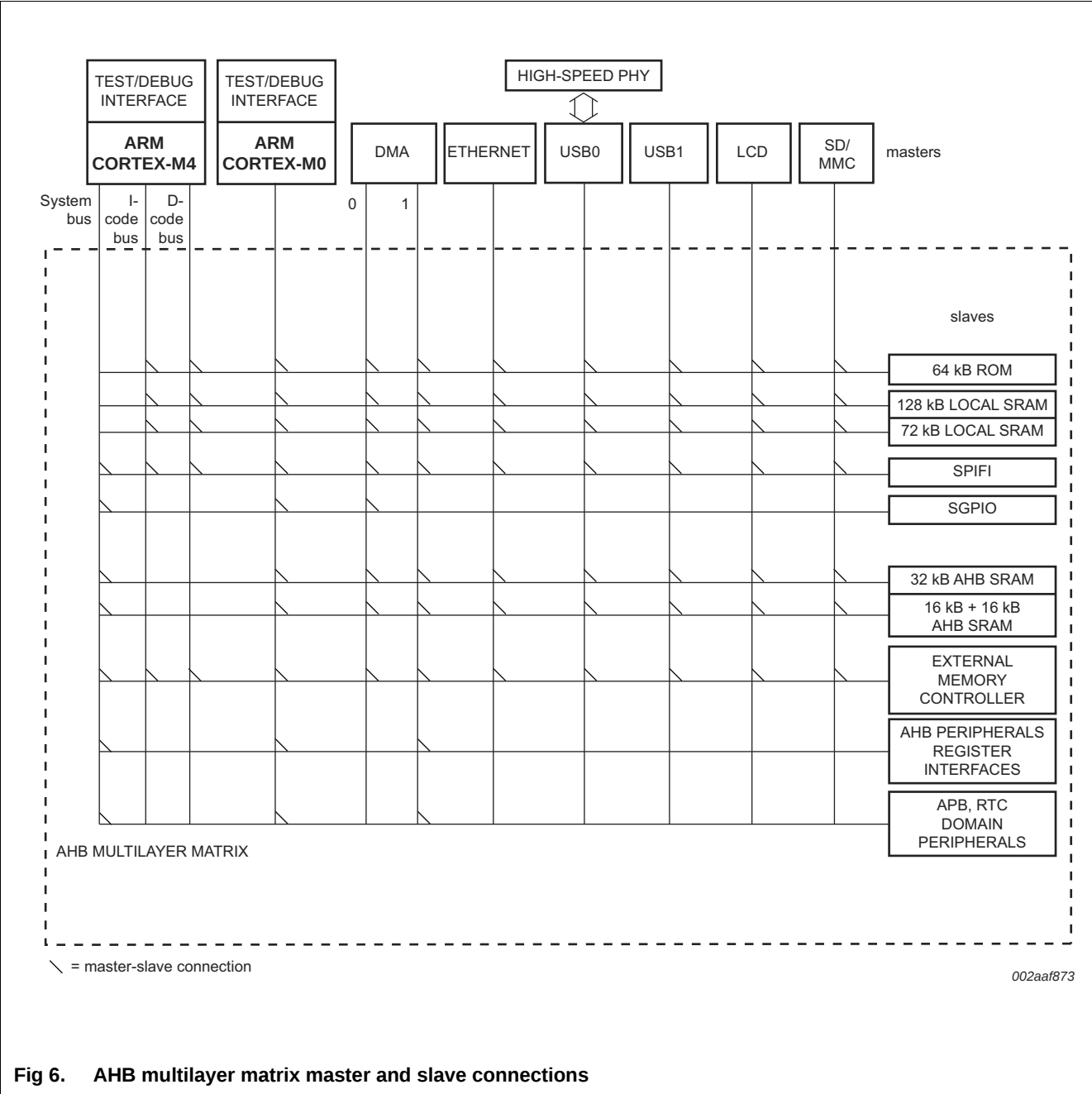


Fig 6. AHB multilayer matrix master and slave connections

7.6 Nested Vectored Interrupt Controller (NVIC)

The NVIC is an integral part of the Cortex-M4. The tight coupling to the CPU allows for low interrupt latency and efficient processing of late arriving interrupts.

The ARM Cortex-M0 coprocessor has its own NVIC with 32 vectored interrupts. Most peripheral interrupts are shared between the Cortex-M0 and Cortex-M4 NVICs.

- Values of Match/Capture registers, plus reload or capture control values

In the two-counter case, the following operational elements are global to the SCTimer/PWM, but the last three can use match conditions from either counter:

- Clock selection
- Inputs
- Events
- Outputs
- Interrupts

7.16.1.1 Features

- Two 16-bit counters or one 32-bit counter.
- Counters clocked by bus clock or selected input.
- Counters can be configured as up-counters or up-down counters.
- State variable allows sequencing across multiple counter cycles.
- Event combines input or output condition and/or counter match in a specified state.
- Events control outputs and interrupts.
- Selected events can limit, halt, start, or stop a counter.
- Supports:
 - up to 8 inputs
 - 16 outputs
 - 16 match/capture registers
 - 16 events
 - 32 states

7.16.2 Serial GPIO (SGPIO)

The Serial GPIOs offer standard GPIO functionality enhanced with features to accelerate serial stream processing.

7.16.2.1 Features

- Each SGPIO input/output slice can be used to perform a serial to parallel or parallel to serial data conversion.
- 16 SGPIO input/output slices each with a 32-bit FIFO that can shift the input value from a pin or an output value to a pin with every cycle of a shift clock.
- Each slice is double-buffered.
- Interrupt is generated on a full FIFO, shift clock, or pattern match.
- Slices can be concatenated to increase buffer size.
- Each slice has a 32-bit pattern match filter.

- Configurable word select period in master mode (separately for I²S-bus input and output).
- Two 8-word FIFO data buffers are provided, one for transmit and one for receive.
- Generates interrupt requests when buffer levels cross a programmable boundary.
- Two DMA requests controlled by programmable buffer levels. The DMA requests are connected to the GPDMA block.
- Controls include reset, stop and mute options separately for I²S-bus input and I²S-bus output.

7.18.7 C_CAN

Remark: The LPC43S50/S30/S20 contain two C_CAN controllers.

Controller Area Network (CAN) is the definition of a high performance communication protocol for serial data communication. The C_CAN controller is designed to provide a full implementation of the CAN protocol according to the CAN Specification Version 2.0B. The C_CAN controller can create powerful local networks with low-cost multiplex wiring by supporting distributed real-time control with a high level of reliability.

7.18.7.1 Features

- Conforms to protocol version 2.0 parts A and B.
- Supports bit rate of up to 1 Mbit/s.
- Supports 32 Message Objects.
- Each Message Object has its own identifier mask.
- Provides programmable FIFO mode (concatenation of Message Objects).
- Provides maskable interrupts.
- Supports Disabled Automatic Retransmission (DAR) mode for time-triggered CAN applications.
- Provides programmable loop-back mode for self-test operation.

7.19 Counter/timers and motor control

7.19.1 General purpose 32-bit timers/external event counters

The LPC43S50/S30/S20 include four 32-bit timer/counters. The timer/counter is designed to count cycles of the system derived clock or an externally-supplied clock. It can optionally generate interrupts, generate timed DMA requests, or perform other actions at specified timer values, based on four match registers. Each timer/counter also includes two capture inputs to trap the timer value when an input signal transitions, optionally generating an interrupt.

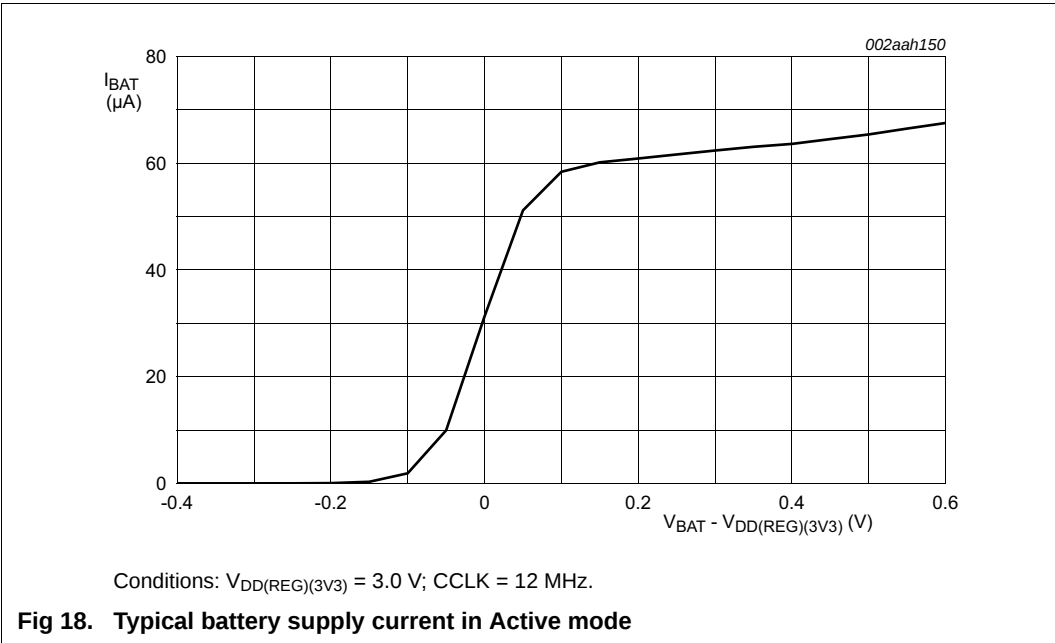
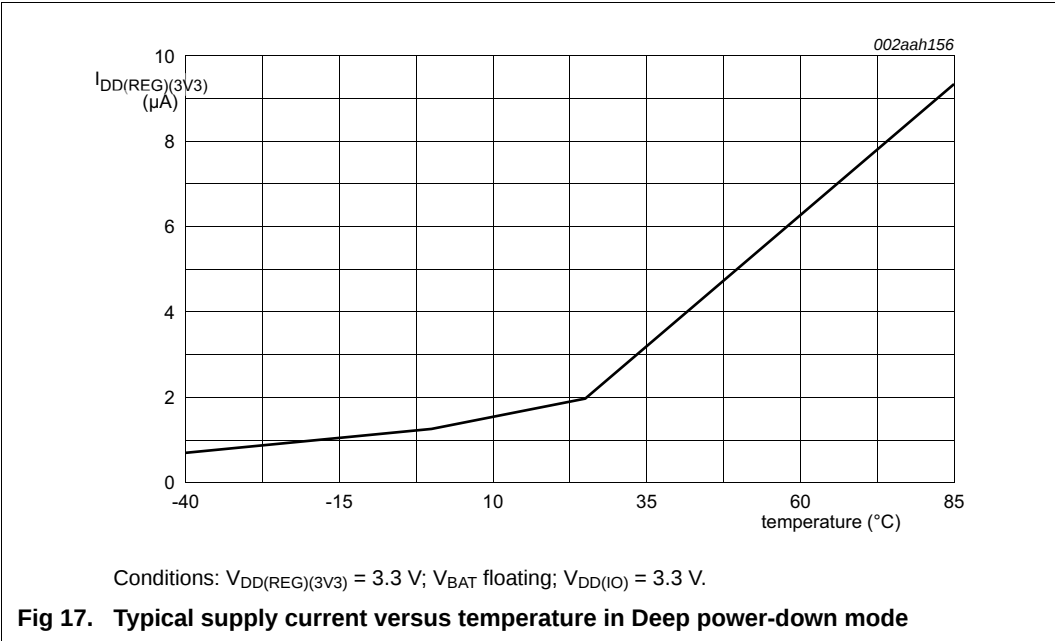
7.19.1.1 Features

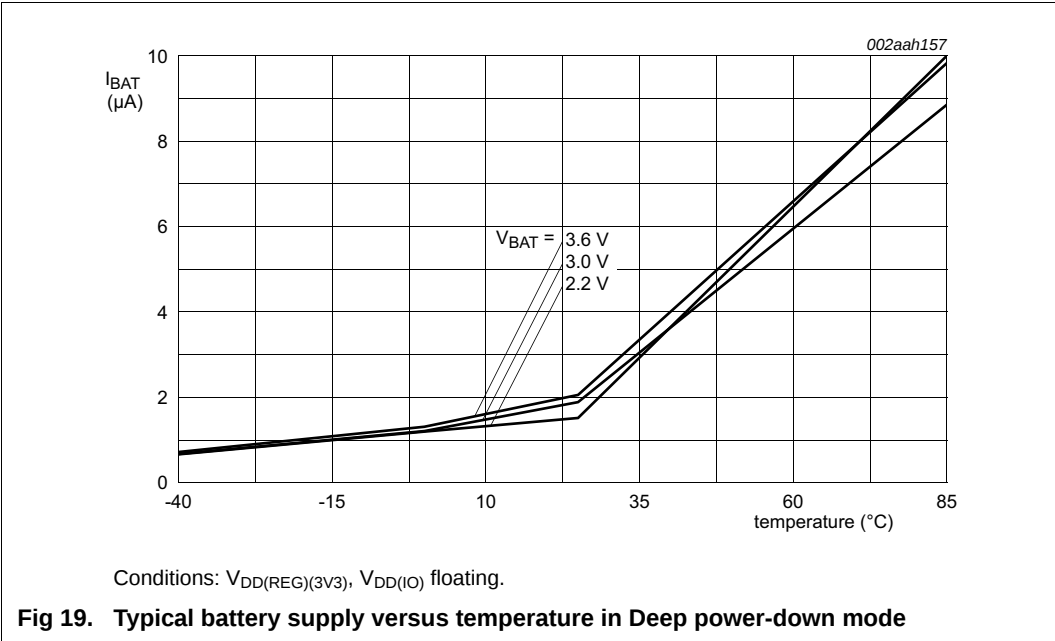
- A 32-bit timer/counter with a programmable 32-bit prescaler.
- Counter or timer operation.
- Two 32-bit capture channels per timer, that can take a snapshot of the timer value when an input signal transitions. A capture event can also generate an interrupt.
- Four 32-bit match registers that allow:

Table 10. Static characteristics ...continued

 $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ ^[1]	Max	Unit
I _{pu}	pull-up current	V _I = 0 V	^[14] ^[15] ^[16]	-	-62	-	μA
		V _{DD(IO)} < V _I ≤ 5 V		-	10	-	μA
I/O pins - high drive strength: standard drive mode							
I _{OH}	HIGH-level output current	V _{OH} = V _{DD(IO)} – 0.4 V		–4	-	-	mA
I _{OL}	LOW-level output current	V _{OL} = 0.4 V		4	-	-	mA
I _{OHS}	HIGH-level short-circuit output current	drive HIGH; connected to ground	^[12]	-	-	32	mA
I _{OLS}	LOW-level short-circuit output current	drive LOW; connected to V _{DD(IO)}	^[12]	-	-	32	mA
I/O pins - high drive strength: medium drive mode							
I _{OH}	HIGH-level output current	V _{OH} = V _{DD(IO)} – 0.4 V		–8	-	-	mA
I _{OL}	LOW-level output current	V _{OL} = 0.4 V		8	-	-	mA
I _{OHS}	HIGH-level short-circuit output current	drive HIGH; connected to ground	^[12]	-	-	65	mA
I _{OLS}	LOW-level short-circuit output current	drive LOW; connected to V _{DD(IO)}	^[12]	-	-	63	mA
I/O pins - high drive strength: high drive mode							
I _{OH}	HIGH-level output current	V _{OH} = V _{DD(IO)} – 0.4 V		–14	-	-	mA
I _{OL}	LOW-level output current	V _{OL} = 0.4 V		14	-	-	mA
I _{OHS}	HIGH-level short-circuit output current	drive HIGH; connected to ground	^[12]	-	-	113	mA
I _{OLS}	LOW-level short-circuit output current	drive LOW; connected to V _{DD(IO)}	^[12]	-	-	110	mA
I/O pins - high drive strength: ultra-high drive mode							
I _{OH}	HIGH-level output current	V _{OH} = V _{DD(IO)} – 0.4 V		–20	-	-	mA
I _{OL}	LOW-level output current	V _{OL} = 0.4 V		20	-	-	mA
I _{OHS}	HIGH-level short-circuit output current	drive HIGH; connected to ground	^[12]	-	-	165	mA
I _{OLS}	LOW-level short-circuit output current	drive LOW; connected to V _{DD(IO)}	^[12]	-	-	156	mA
I/O pins - high-speed							
C _I	input capacitance			-	-	2	pF
I _{LL}	LOW-level leakage current	V _I = 0 V; on-chip pull-up resistor disabled		-	3	-	nA





10.2 Peripheral power consumption

The typical power consumption at T = 25 °C for each individual peripheral is measured as follows:

1. Enable all branch clocks and measure the current $I_{DD(REG)(3V3)}$.
2. Disable the branch clock to the peripheral to be measured and keep all other branch clocks enabled.
3. Calculate the difference between measurement 1 and 2. The result is the peripheral power consumption.

Table 11. Peripheral power consumption

Peripheral	Branch clock	$I_{DD(REG)(3V3)}$ in mA	
		Branch clock frequency = 48 MHz	Branch clock frequency = 96 MHz
M0 core	CLK_M4_M0APP	3.3	6.6
I2C1	CLK_APB3_I2C1	0.01	0.02
I2C0	CLK_APB1_I2C0	0.02	0.01
DAC	CLK_APB3_DAC	0.01	0.02
ADC0	CLK_APB3_ADC0	0.05	0.05
ADC1	CLK_APB3_ADC1	0.04	0.04
CAN0	CLK_APB3_CAN0	0.17	0.17
CAN1	CLK_APB1_CAN1	0.17	0.17
MOTOCON	CLK_APB1_MOTOCON	0.05	0.05
I2S	CLK_APB1_I2S	0.11	0.11
SPIFI	CLK_SPIFI, CLK_M4_SPIFI	0.95	1.85
GPIO	CLK_M4_GPIO	0.66	1.31

11. Dynamic characteristics

11.1 Wake-up times

Table 14. Dynamic characteristic: Wake-up from Deep-sleep, Power-down, and Deep power-down modes

$T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$

Symbol	Parameter	Conditions		Min	Typ ^[1]	Max	Unit
t_{wake}	wake-up time	from Sleep mode	[2]	$3 \times T_{cy(clk)}$	$5 \times T_{cy(clk)}$	-	ns
		from Deep-sleep and Power-down mode		12	51	-	μs
		from Deep power-down mode		-	250	-	μs
		after reset		-	250	-	μs

[1] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

[2] $T_{cy(clk)} = 1/\text{CCLK}$ with CCLK = CPU clock frequency.

11.2 External clock for oscillator in slave mode

Remark: The input voltage on the XTAL1/2 pins must be $\leq 1.2\text{ V}$ (see Table 10). For connecting the oscillator to the XTAL pins, also see [Section 13.2](#) and [Section 13.4](#).

Table 15. Dynamic characteristic: external clock

$T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}$; $V_{DD(I/O)}$ over specified ranges.^[1]

Symbol	Parameter	Conditions		Min	Max	Unit
f_{osc}	oscillator frequency			1	25	MHz
$T_{cy(clk)}$	clock cycle time			40	1000	ns
t_{CHCX}	clock HIGH time			$T_{cy(clk)} \times 0.4$	$T_{cy(clk)} \times 0.6$	ns
t_{CLCX}	clock LOW time			$T_{cy(clk)} \times 0.4$	$T_{cy(clk)} \times 0.6$	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

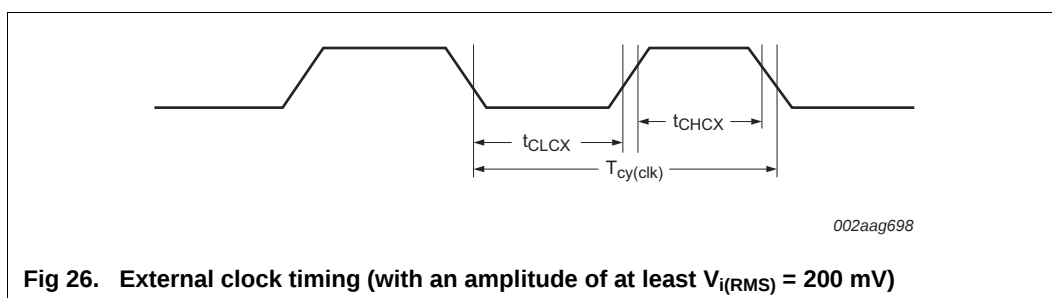


Table 28. Dynamic characteristics: Dynamic external memory interface

Simulated data over temperature and process range; $C_L = 10$ pF for $\overline{EMC_DYCSn}$, $\overline{EMC_RAS}$, $\overline{EMC_CAS}$, $\overline{EMC_WE}$, $\overline{EMC_An}$; $C_L = 9$ pF for $\overline{EMC_Dn}$; $C_L = 5$ pF for $\overline{EMC_DQMOUTn}$, $\overline{EMC_CLKn}$, $\overline{EMC_CKEOUTn}$; $T_{amb} = -40$ °C to 85 °C; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$; $V_{DD(IO)} = 3.3\text{ V} \pm 10\%$; $RD = 1$ (see LPC43xx User manual); $\overline{EMC_CLKn}$ delays $CLK0_DELAY = CLK1_DELAY = CLK2_DELAY = CLK3_DELAY = 0$.

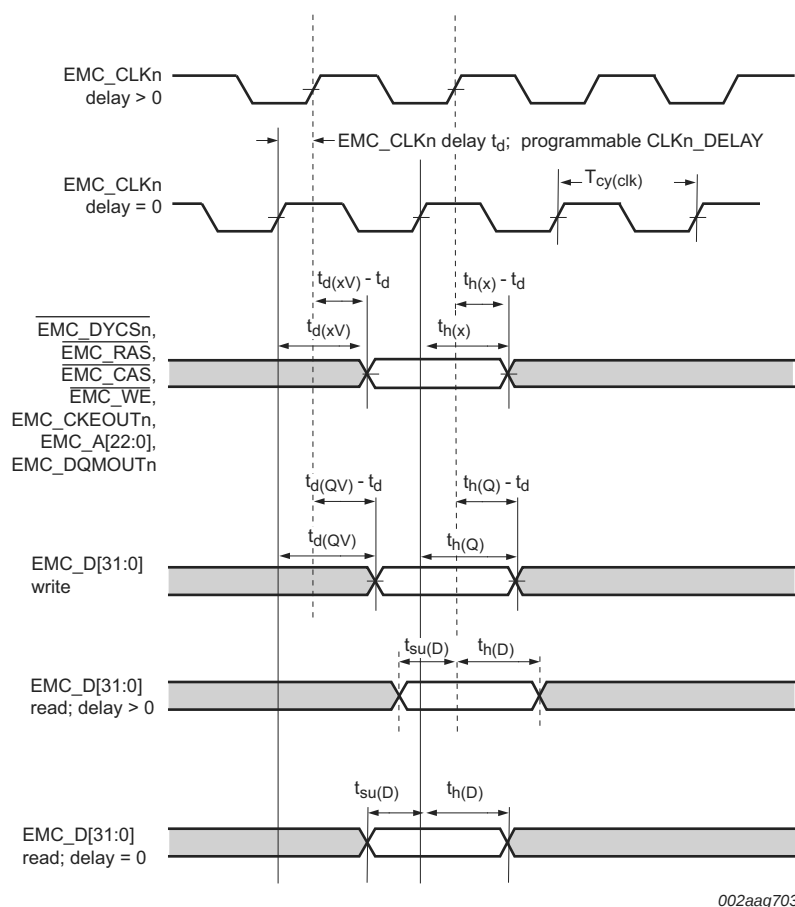
Symbol	Parameter	Min	Typ	Max	Unit
$T_{cy(clk)}$	clock cycle time	8.4	-	-	ns
Common to read and write cycles					
$t_{d(DYCSV)}$	DYCS delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$5.1 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(DYCS)}$	DYCS hold time	$0.3 + 0.5 \times T_{cy(clk)}$	$0.9 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(RASV)}$	row address strobe valid delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$4.9 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(RAS)}$	row address strobe hold time	$0.5 + 0.5 \times T_{cy(clk)}$	$1.1 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(CASV)}$	column address strobe valid delay time	-	$2.9 + 0.5 \times T_{cy(clk)}$	$4.6 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(CAS)}$	column address strobe hold time	$0.3 + 0.5 \times T_{cy(clk)}$	$0.9 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(WEV)}$	$\overline{WE}$ valid delay time	-	$3.2 + 0.5 \times T_{cy(clk)}$	$5.9 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(WE)}$	$\overline{WE}$ hold time	$1.3 + 0.5 \times T_{cy(clk)}$	$1.4 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(DQMOUTV)}$	DQMOUT valid delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$5.0 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(DQMOUT)}$	DQMOUT hold time	$0.2 + 0.5 \times T_{cy(clk)}$	$0.8 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(AV)}$	address valid delay time	-	$3.8 + 0.5 \times T_{cy(clk)}$	$6.3 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(A)}$	address hold time	$0.3 + 0.5 \times T_{cy(clk)}$	$0.9 + 0.5 \times T_{cy(clk)}$	-	ns
$t_{d(CKEOUTV)}$	CKEOUT valid delay time	-	$3.1 + 0.5 \times T_{cy(clk)}$	$5.1 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(CKEOUT)}$	CKEOUT hold time	$0.5 \times T_{cy(clk)}$	$0.7 + 0.5 \times T_{cy(clk)}$	-	ns
Read cycle parameters					
$t_{su(D)}$	data input set-up time	-1.5	-0.5	-	ns
$t_{h(D)}$	data input hold time	2.2	0.8	-	ns
Write cycle parameters					
$t_{d(QV)}$	data output valid delay time	-	$3.8 + 0.5 \times T_{cy(clk)}$	$6.2 + 0.5 \times T_{cy(clk)}$	ns
$t_{h(Q)}$	data output hold time	$0.5 \times T_{cy(clk)}$	$0.7 + 0.5 \times T_{cy(clk)}$	-	ns

Table 29. Dynamic characteristics: Dynamic external memory interface; EMC_CLK[3:0] delay values

$T_{amb} = -40$ °C to 85 °C; $V_{DD(IO)} = 3.3\text{ V} \pm 10\%$; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_d	delay time	delay value ^[1]				
		CLKn_DELAY = 0	0.0	0.0	0.0	ns
		CLKn_DELAY = 1 ^[1]	0.4	0.5	0.8	ns
		CLKn_DELAY = 2 ^[1]	0.7	1.0	1.7	ns
		CLKn_DELAY = 3 ^[1]	1.1	1.6	2.5	ns
		CLKn_DELAY = 4 ^[1]	1.4	2.0	3.3	ns
		CLKn_DELAY = 5 ^[1]	1.7	2.6	4.1	ns
		CLKn_DELAY = 6 ^[1]	2.1	3.1	4.9	ns
		CLKn_DELAY = 7 ^[1]	2.5	3.6	5.8	ns

[1] Program the EMC_CLKn delay values in the EMCDELAYCLK register (see the LPC43xx User manual). The delay values must be the same for all SDRAM clocks EMC_CLKn: $CLK0_DELAY = CLK1_DELAY = CLK2_DELAY = CLK3_DELAY$.



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For the programmable $EMC_CLK[3:0]$ clock delays $CLKn_DELAY$, see [Table 29](#).

Remark: For SDRAM operation, set $CLK0_DELAY = CLK1_DELAY = CLK2_DELAY = CLK3_DELAY$ in the $EMCDELAYCLK$ register.

Fig 36. SDRAM timing

11.16 USB interface

Table 30. Dynamic characteristics: USB0 and USB1 pins (full-speed)

$C_L = 50\text{ pF}$; $R_{pu} = 1.5\text{ k}\Omega$ on D+ to $V_{DD(I/O)}$; $3.0\text{ V} \leq V_{DD(I/O)} \leq 3.6\text{ V}$.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_r	rise time	10 % to 90 %	4	-	20	ns
t_f	fall time	10 % to 90 %	4	-	20	ns
t_{FRFM}	differential rise and fall time matching	t_r / t_f	90	-	111.11	%
V_{CRS}	output signal crossover voltage		1.3	-	2.0	V
t_{FEOPT}	source SE0 interval of EOP	see Figure 37	160	-	175	ns
t_{FDEOP}	source jitter for differential transition to SE0 transition	see Figure 37	-2	-	+5	ns
t_{JR1}	receiver jitter to next transition		-18.5	-	+18.5	ns
t_{JR2}	receiver jitter for paired transitions	10 % to 90 %	-9	-	+9	ns
t_{EOPR1}	EOP width at receiver	must reject as EOP; see Figure 37	[1]	40	-	ns
t_{EOPR2}	EOP width at receiver	must accept as EOP; see Figure 37	[1]	82	-	ns

[1] Characterized but not implemented as production test. Guaranteed by design.

Remark: If only USB0 (HS USB) is used, the pins VDDREG and VDDIO can be at different voltages within the operating range but should have the same ramp up time. If USB1(FS USB) is used, the pins VDDREG and VDDIO should be a minimum of 3.0 V and be tied together.

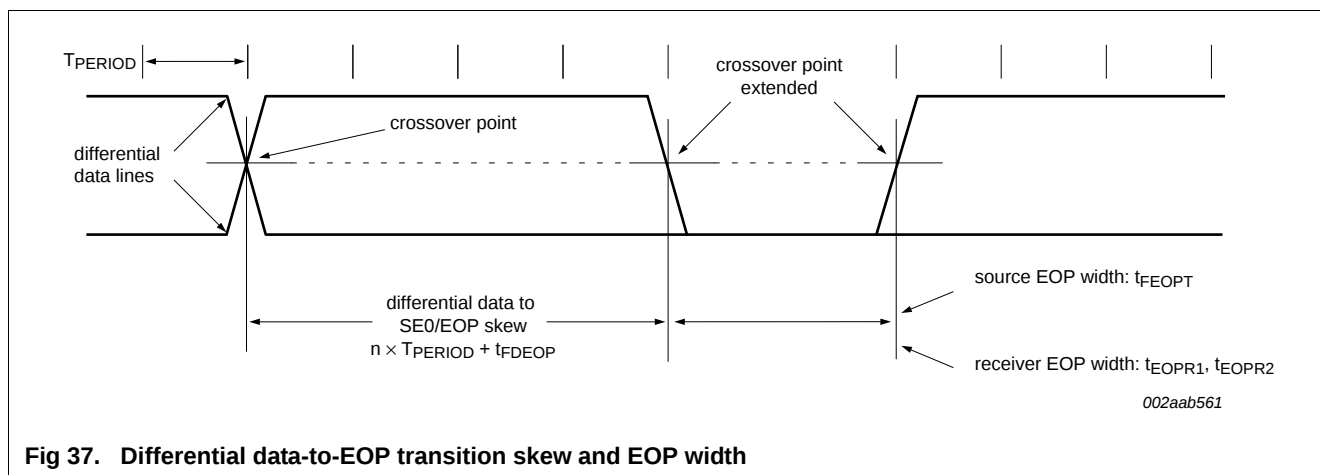


Table 31. Static characteristics: USB0 PHY pins^[1]

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
High-speed mode							
P _{cons}	power consumption		[2]	-	68	-	mW
I _{DDA(3V3)}	analog supply current (3.3 V)	on pin USB0_VDDA3V3_DRIVER; total supply current	[3]	-	18	-	mA
		during transmit		-	31	-	mA
		during receive		-	14	-	mA
		with driver tri-stated		-	14	-	mA
I _{DDD}	digital supply current			-	7	-	mA
Full-speed/low-speed mode							
P _{cons}	power consumption		[2]	-	15	-	mW
I _{DDA(3V3)}	analog supply current (3.3 V)	on pin USB0_VDDA3V3_DRIVER; total supply current		-	3.5	-	mA
		during transmit		-	5	-	mA
		during receive		-	3	-	mA
		with driver tri-stated		-	3	-	mA
I _{DDD}	digital supply current			-	3	-	mA
Suspend mode							
I _{DDA(3V3)}	analog supply current (3.3 V)			-	24	-	μA
		with driver tri-stated		-	24	-	μA
		with OTG functionality enabled		-	3	-	mA
I _{DDD}	digital supply current			-	30	-	μA
VBUS detector outputs							
V _{th}	threshold voltage	for VBUS valid		4.4	-	-	V
		for session end		0.2	-	0.8	V
		for A valid		0.8	-	2	V
		for B valid		2	-	4	V
V _{hys}	hysteresis voltage	for session end		-	150	10	mV
		A valid		-	200	10	mV
		B valid		-	200	10	mV

[1] Characterized but not implemented as production test.

[2] Total average power consumption.

[3] The driver is active only 20 % of the time.

11.17 Ethernet

Remark: The timing characteristics of the ENET_MDC and ENET_MDIO signals comply with the *IEEE standard 802.3*.

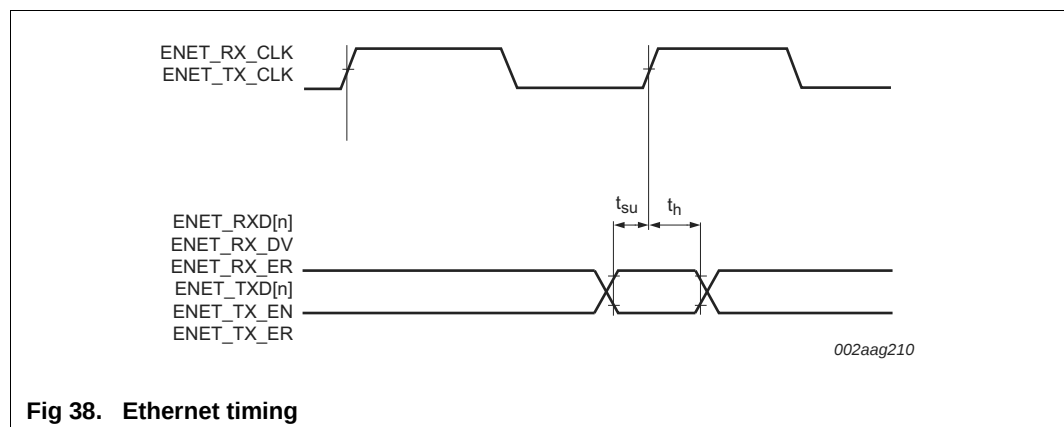
Table 32. Dynamic characteristics: Ethernet

$T_{amb} = -40\text{ }^{\circ}\text{C}$ to $85\text{ }^{\circ}\text{C}$; $2.2\text{ V} \leq V_{DD(REG)(3V3)} \leq 3.6\text{ V}$; $2.7\text{ V} \leq V_{DD(IO)} \leq 3.6\text{ V}$. Values guaranteed by design.

Symbol	Parameter	Conditions		Min	Max	Unit
RMII mode						
f_{clk}	clock frequency	for ENET_RX_CLK	[1]	-	50	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns
t_h	hold time	for ENET_TXDn, ENET_TX_EN, ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	2	-	ns
MII mode						
f_{clk}	clock frequency	for ENET_TX_CLK	[1]	-	25	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	[1][2]	4	-	ns
t_h	hold time	for ENET_TXDn, ENET_TX_EN, ENET_TX_ER	[1][2]	2	-	ns
f_{clk}	clock frequency	for ENET_RX_CLK	[1]	-	25	MHz
δ_{clk}	clock duty cycle		[1]	50	50	%
t_{su}	set-up time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	4	-	ns
t_h	hold time	for ENET_RXDn, ENET_RX_ER, ENET_RX_DV	[1][2]	2	-	ns

[1] Output drivers can drive a load $\geq 25\text{ pF}$ accommodating over 12 inch of PCB trace and the input capacitance of the receiving device.

[2] Timing values are given from the point at which the clock signal waveform crosses 1.4 V to the valid input or output level.

**Fig 38. Ethernet timing**